



## **SPECIFICATION**

• Supplier : Samsung electro-mechanics • Samsung P/N : CL10C470JB8NFNC

• Product : Multi-layer Ceramic Capacitor • Description : CAP, 47pF, 50V, ±5%, C0G, 0603

## A. Samsung Part Number

<u>CL</u> <u>10</u> <u>C</u> <u>470</u> <u>J</u> <u>B</u> <u>8</u> <u>N</u> <u>F</u> <u>N</u> <u>C</u> ① ② ③ ④ ⑤ ⑥ ⑦ 8 ⑨ ⑩ ⑪

① S	Series	Samsung Multi-layer Ceramic Capacitor							
② S	Size	0603 (inch c	ode) L:	1.6	± 0.1	mm	W:	$0.8 \pm 0.1$	mm
(3) E	Dielectric	COG		<b>(8</b> )	Inner el	ectrode	N	li	
_	Capacitance	<b>47</b> pF		Ŭ	Termina		С	u	
⑤ C	Capacitance	±5 %			Plating		S	n 100%	(Pb Free)
te	olerance			9	Product	t	Р	roduct for P	OWER application
6 R	Rated Voltage	50 V		10	Special		R	eserved for	future use
⑦ T	Thickness	$0.8 \pm 0.1$	mm	11)	Packagi	ing	С	ardboard T	ype, 7" reel

## **B. Samsung Reliablility Test and Judgement condition**

	Performance	Test condition				
Capacitance	Within specified tolerance	1Mb±10% 0.5~5Vrms				
Q	1000 min					
Insulation	10,000Mohm or 500Mohm⋅ <i>μ</i> F	Rated Voltage 60~120 sec.				
Resistance	Whichever is Smaller					
Appearance	No abnormal exterior appearance	Microscope (×10)				
Withstanding	No dielectric breakdown or	300% of the rated voltage				
Voltage	mechanical breakdown					
Temperature	COG					
Characterisitcs	shoud be within ±30PPM/℃)					
Adhesive Strength	No peeling shall be occur on the	500g·F, for 10±1 sec.				
of Termination	terminal electrode					
Bending Strength	Capacitance change :	Bending to the limit (1mm)				
	within ±5% or ±0.5pF whichever is larger	with 1.0mm/sec.				
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder				
	is to be soldered newly	245±5℃, 3±0.3sec.				
		(preheating : 80~120 ℃ for 10~30sec.)				
Resistance to Capacitance change :		Solder pot : 270±5℃, 10±1sec.				
Soldering heat	within ±2.5% or ±0.25pF whichever is larger					
	Tan δ, IR : initial spec.					

	Performance	Test condition					
Vibration Test	Capacitance change :	Amplitude : 1.5mm					
	within ±2.5% or ±0.25pF whichever is larger	From 10Hz to 55Hz (return : 1min.)					
	Tan δ, IR : initial spec.	2hours × 3 direction (x, y, z)					
Moisture	Capacitance change :	With rated voltage					
Resistance	within ±7.5% or ±0.75pF whichever is larger	40±2℃, 90~95%RH, 500+12/-0hrs					
	Q: 200 min						
	IR : 500Mohm or 25Mohm $\cdot \mu$ F						
	Whichever is Smaller						
High Temperature	Capacitance change :	With 200% of the rated voltage					
Resistance	within ±3% or ±0.3pF whichever is larger	Max. operating temperature					
	Q: 350 min	1000+48/-0hrs					
	IR : 1000Mohm or 50Mohm $\cdot \mu$ F						
	Whichever is Smaller						
Temperature	Capacitance change :	1 cycle condition					
Cycling	within ±2.5% or ±0.25pF whichever is larger	Min. operating temperature → 25°C					
	Tan δ, IR : initial spec.	→ Max. operating temperature → 25°C					
		5 cycle test					

## C. Recommended Soldering method :

Reflow ( Reflow Peak Temperature : 260+0/-5  $^{\circ}$ C , 10sec. Max )

<sup>\*</sup> For the more detail Specification, Please refer to the Samsung MLCC catalogue.